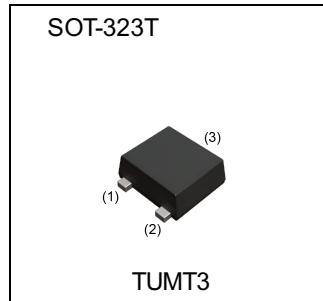


Parameter	Value
$V_{CEO}$	30V
$I_C$	1.5A

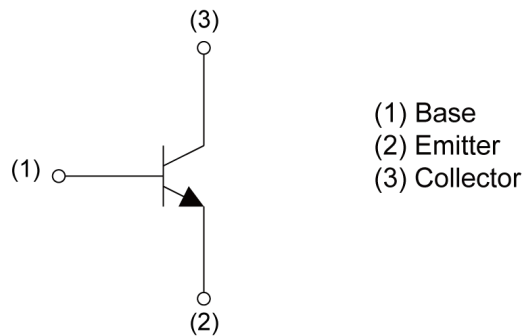
●Outline



●Features

- 1) Collector current is large.
- 2)  $V_{CE(sat)} \leq 350mV$   
at  $I_C = 1A / I_B = 50mA$
- 3) Complementary PNP Types : 2SB1731

●Inner circuit



●Application

LOW FREQUENCY AMPLIFIER

●Packaging specifications

Part No.	Package	Package size	Taping code	Reel size (mm)	Tape width (mm)	Basic ordering unit.(pcs)	Marking
2SD2701	SOT-323T (TUMT3)	2021	TL	180	8	3000	FZ

● **Absolute maximum ratings** ( $T_a = 25^\circ\text{C}$ )

Parameter	Symbol	Values	Unit
Collector-base voltage	$V_{\text{CBO}}$	30	V
Collector-emitter voltage	$V_{\text{CEO}}$	30	V
Emitter-base voltage	$V_{\text{EBO}}$	6	V
Collector current	$I_{\text{C}}$	1.5	A
	$I_{\text{CP}}^{*1}$	3	A
Power dissipation	$P_{\text{D}}^{*2}$	0.4	W
	$P_{\text{D}}^{*3}$	0.8	W
Junction temperature	$T_{\text{j}}$	150	$^\circ\text{C}$
Range of storage temperature	$T_{\text{stg}}$	-55 to +150	$^\circ\text{C}$

● **Electrical characteristics** ( $T_a = 25^\circ\text{C}$ )

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Collector-base breakdown voltage	$BV_{\text{CBO}}$	$I_{\text{C}} = 10\mu\text{A}$	30	-	-	V
Collector-emitter breakdown voltage	$BV_{\text{CEO}}$	$I_{\text{C}} = 1\text{mA}$	30	-	-	V
Emitter-base breakdown voltage	$BV_{\text{EBO}}$	$I_{\text{E}} = 10\mu\text{A}$	6	-	-	V
Collector cut-off current	$I_{\text{CBO}}$	$V_{\text{CB}} = 30\text{V}$	-	-	100	nA
Emitter cut-off current	$I_{\text{EBO}}$	$V_{\text{EB}} = 6\text{V}$	-	-	100	nA
Collector-emitter saturation voltage	$V_{\text{CE(sat)}}$	$I_{\text{C}} = 1\text{A}, I_{\text{B}} = 50\text{mA}$	-	140	350	mV
DC current gain	$h_{\text{FE}}$	$V_{\text{CE}} = 2\text{V}, I_{\text{C}} = 100\text{mA}$	270	-	680	-
Transition frequency	$f_{\text{T}}$	$V_{\text{CE}} = 2\text{V}, I_{\text{E}} = -100\text{mA}, f = 100\text{MHz}$	-	300	-	MHz
Output capacitance	$C_{\text{ob}}$	$V_{\text{CB}} = 10\text{V}, I_{\text{E}} = 0\text{A}, f = 1\text{MHz}$	-	11	-	pF

\*1  $P_w=1\text{ms}$  Single Pulse

\*2 Each terminal mounted on a reference land.

\*3 Mounted on a ceramic board(25×25×0.8 mm).

● Electrical characteristic curves ( $T_a = 25^\circ\text{C}$ )

Fig.1 Ground Emitter Propagation Characteristics

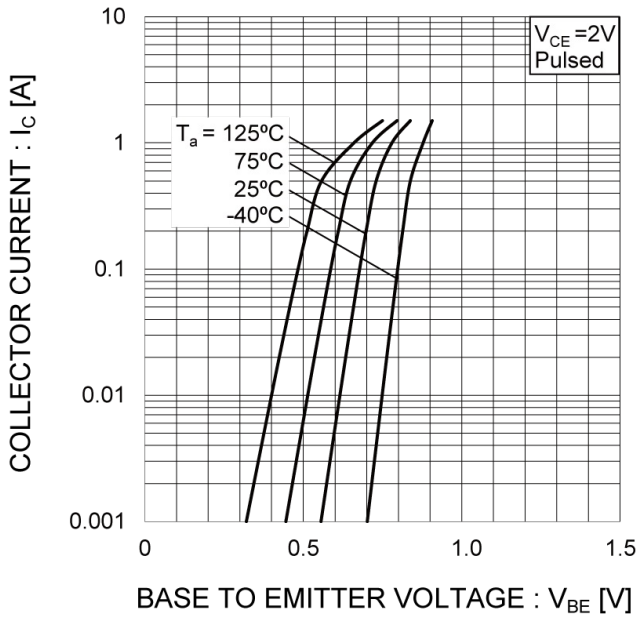


Fig.2 Typical Output Characteristics

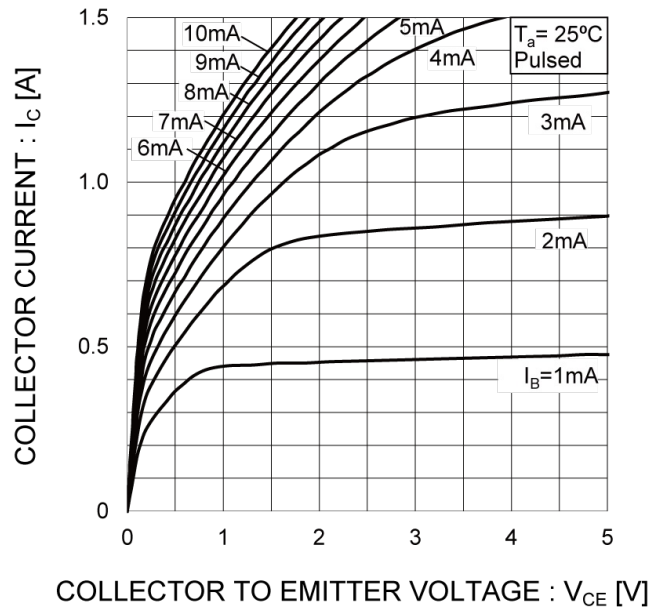


Fig.3 DC Current Gain vs. Collector Current (I)

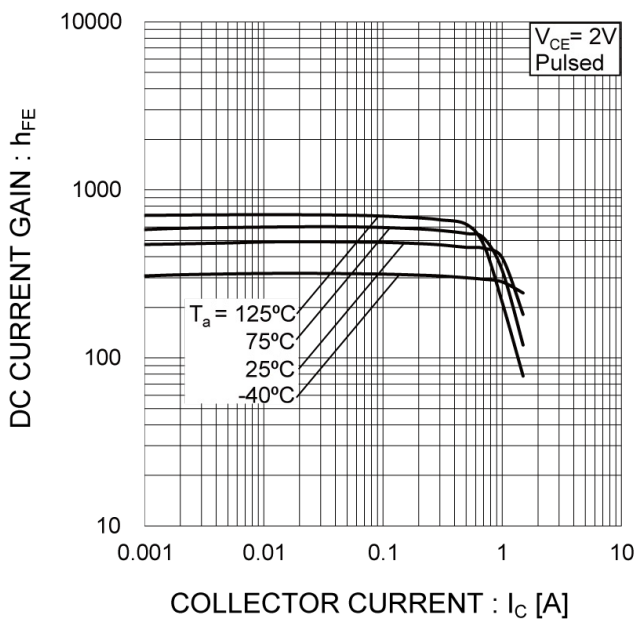
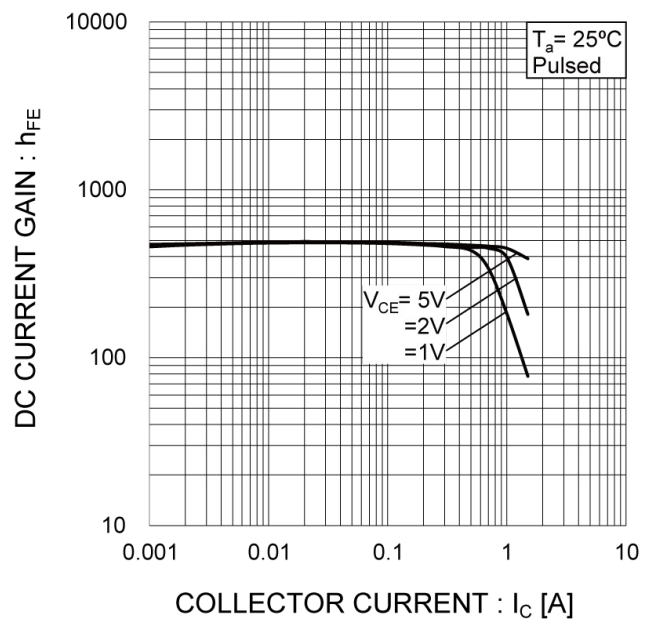


Fig.4 DC Current Gain vs. Collector Current (II)



● Electrical characteristic curves ( $T_a = 25^\circ\text{C}$ )

Fig.5 Collector-Emitter Saturation Voltage vs. Collector Current (I)

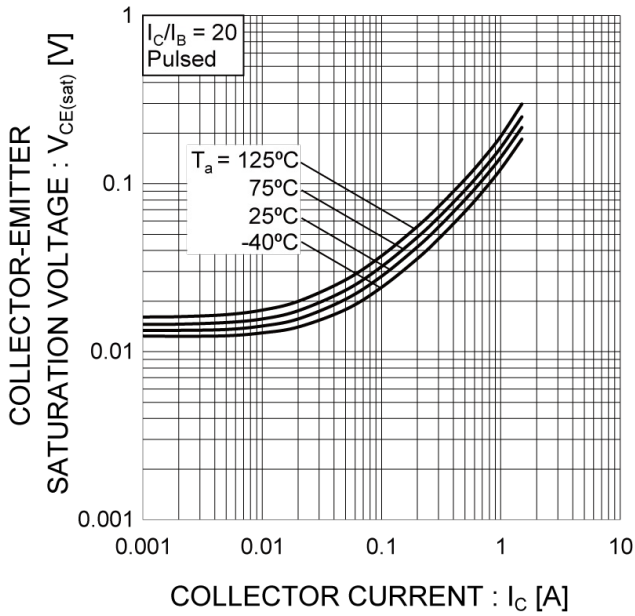


Fig.6 Collector-Emitter Saturation Voltage vs. Collector Current (II)

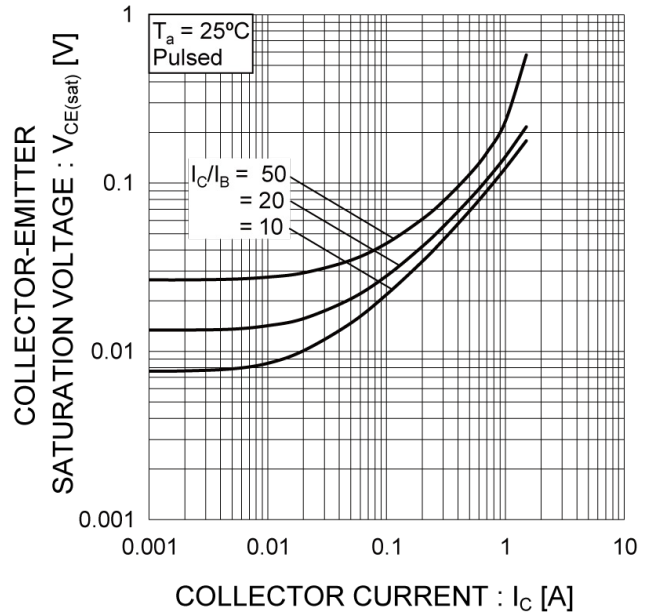


Fig.7 Base-Emitter Saturation Voltage vs. Collector Current

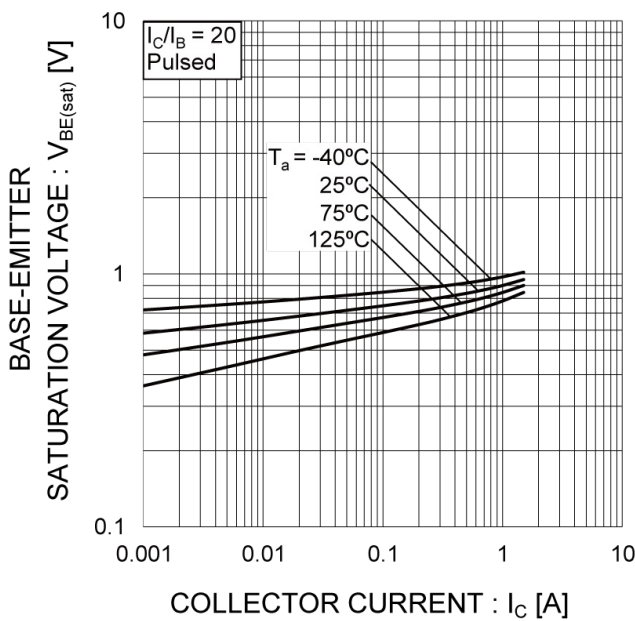
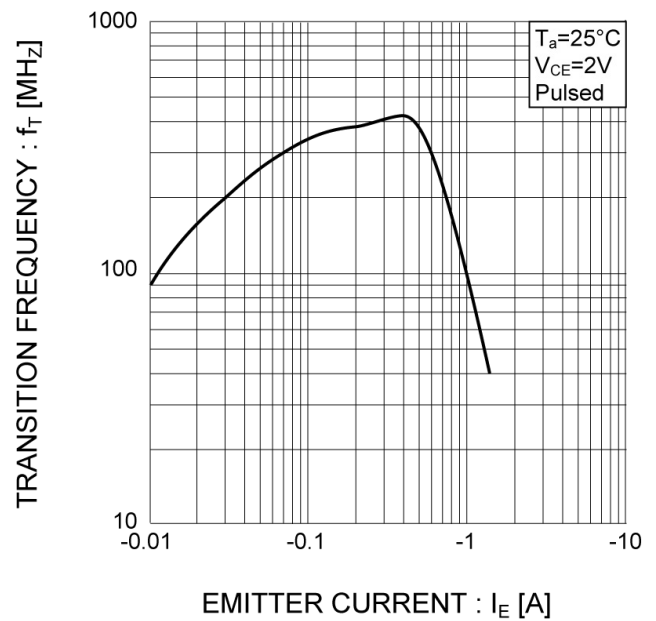


Fig.8 Gain Bandwidth Product vs. Emitter Current



●Electrical characteristic curves( $T_a = 25^\circ\text{C}$ )

Fig.9 Emitter Input Capacitance vs.  
Emitter-Base Voltage  
Collector Output Capacitance vs.  
Collector-Base Voltage

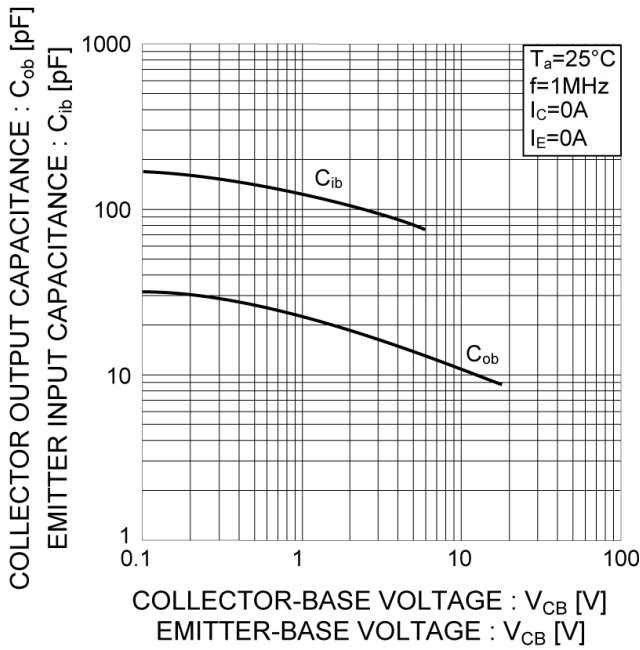
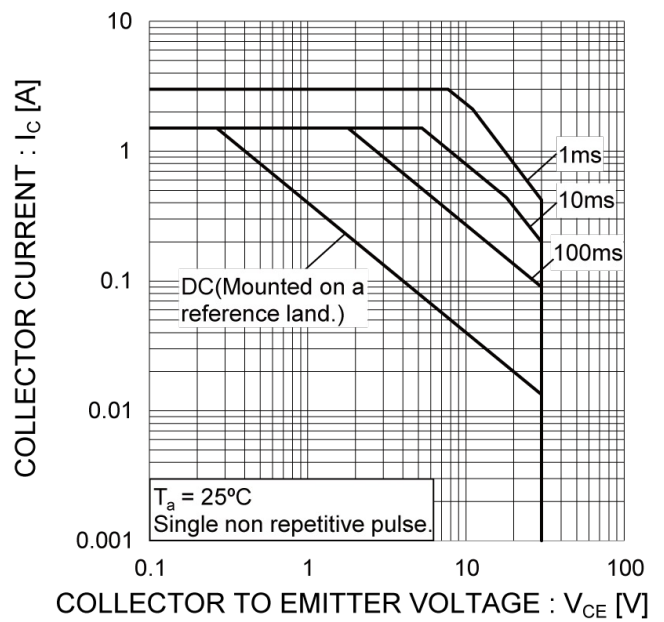
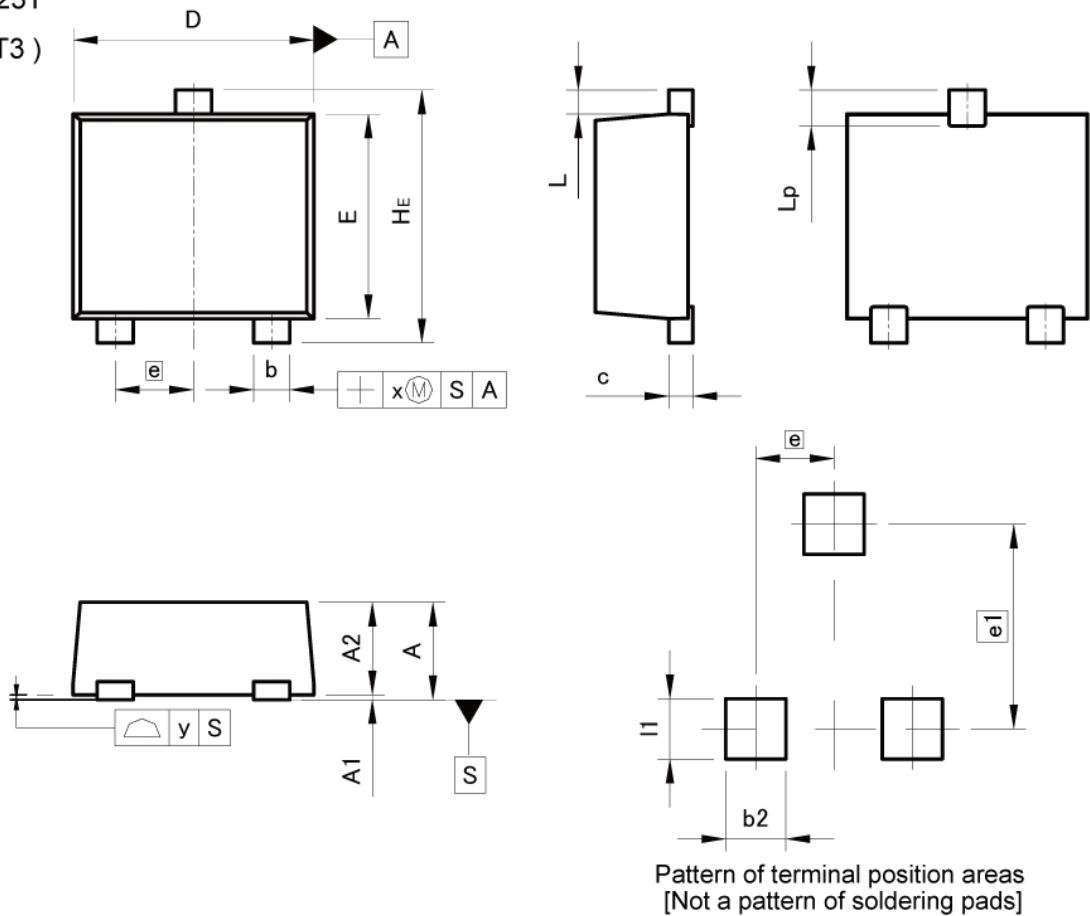


Fig.10 Safe Operating Area



●Dimensions

SOT-323T  
(TUMT3)



DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	-	0.85	-	0.033
A1	0.00	0.10	0.000	0.004
A2	0.72	0.82	0.028	0.032
b	0.25	0.40	0.010	0.016
c	0.12	0.22	0.005	0.009
D	1.90	2.10	0.075	0.083
E	1.60	1.80	0.063	0.071
e	0.65		0.026	
HE	2.00	2.20	0.079	0.087
L	0.20		0.008	
Lp	-	0.40	-	0.016
x	-	0.10	-	0.004
y	-	0.10	-	0.004

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
b2	-	0.50	-	0.020
e1	1.70		0.067	
l1	-	0.50	-	0.020

Dimension in mm/inches

# Notice

## Precaution on using ROHM Products

- Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment <sup>(Note 1)</sup>, transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASS III	CLASS III	CLASS II b	CLASS III
CLASS IV		CLASS III	

- ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
  - Installation of protection circuits or other protective devices to improve system safety
  - Installation of redundant circuits to reduce the impact of single or multiple circuit failure
- Our Products are designed and manufactured for use under standard conditions and not under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc. prior to use, must be necessary:
  - Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
  - Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - Sealing or coating our Products with resin or other coating materials
  - Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - Use of the Products in places subject to dew condensation
- The Products are not subject to radiation-proof design.
- Please verify and confirm characteristics of the final or mounted products in using the Products.
- In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

## Precaution for Mounting / Circuit board design

- When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification